

IEC 60191-6-6 Ed. 1.0 En:2001, Mechanical Standardization Of Semiconductor Devices - Part 6-6: General Rules For The Preparation Of Outline Drawings ... Guide For Fine Pitch Land Grid Array (FLGA) By IEC TC/SC 47D

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6 60191-6-2 IEC:2001(E) 4.1 Outline dimensions The ball terminal dimensions
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